ISSM2020 –International Symposium on Semiconductor Manufacturing
SPONSORSHIP
December 15-16, 2020, Tokyo, Japan

Shozo Saito
Chairman, ISSM2020 Organizing Committee
Device & System Platform Development Center Co., Ltd.
Shuichi Inoue, ATONARP INC.

It is our great pleasure to announce that The 28th annual International Symposium on Semiconductor Manufacturing (ISSM) 2020 will be held on December 15-16, 2020 at KFC Hall, Ryogoku, Tokyo in cooperation with e-Manufacturing & Design Collaboration Symposium (eMDC) which is sponsored by TSIA with support from SEMI and GSA.

The program will feature keynote speeches by world leading speakers, timely and highlighted topics and networking sessions focusing on equipment/materials/software/services with suppliers' exhibits. ISSM continues to contribute to the growth of the semiconductor industry through its infrastructure for networking, discussion, and information sharing among the world's professionals.

We would like you to cooperate with us by supporting the ISSM 2020.

Please see the benefit of ISSM2020 sponsorship.

Conference Overview

Date: December 15-16, 2020
Location: KFC (Kokusai Fashion Center) Hall
1-6-1 Yokoami Sumidaku,
Tokyo 130-0015 Japan
+81-3-5610-5810

Co-Sponsored by: IEEE Electron Devices Society
Minimal Fab
Semiconductor Equipment Association of Japan (SEAJ)
Semiconductor Equipment and Materials International (SEMI)
Taiwan Semiconductor Industry Association (TSIA)

Endorsement by: The Japan Society of Applied Physics

Area of Interest:

Fab Management
Factory Design & Automated Material Handling (FD)
Manufacturing Strategy and Operation Management (MS)
Manufacturing Control and Execution (MC)
Environment, Safety and Health (ES)

Process Integration
Process and Material Optimization (PO)
Yield Enhancement Methodology (YE)
Contamination Control and Ultraclean Technology (UC)
Process Control and Monitoring (PC)
Process and Metrology Equipment (PE)
Design for Manufacturing (DM)

Final Manufacturing
Final Manufacturing (FM)

About ISSM

Semiconductor manufacturing technology is reliant on the sum of the total of engineers' experiences and the accumulation of know-how and IP. The complexity of the field prevents a shift to the systematization and universalization of technologies. In order to bring breakthroughs in semiconductor manufacturing to reflect changing and challenging new requirements, the International Symposium on Semiconductor Manufacturing (ISSM) was launched in 1992.

ISSM is an annual conference of semiconductor manufacturing professionals dedicated to sharing technical solutions and opinions on the advancement of manufacturing science, technologies, and management disciplines. ISSM aims to establish new concepts for semiconductor manufacturing technologies and to promote them as systemized and universalized technologies. ISSM's role has been to challenge the concept of shifting from "know-how" to "science" in semiconductor manufacturing technologies. The past symposia have helped to shape the course of development of "manufacturing science," as well as to create new manufacturing technologies.

The Symposium is held under the joint sponsorship of the IEEE Electron Devices Society, Minimal Fab, Semiconductor Equipment and Materials International (SEMI), and Taiwan Semiconductor Industry Association (TSIA). ISSM, with its global range, continuously pushes technological development in order to promote the discovery and utilization of innovative technologies.

ISSM's mission is to achieve the continued prosperity of the semiconductor industry by bringing about breakthroughs in semiconductor manufacturing technologies through networking between engineers in research and development fields and their counterparts in the manufacturing field.

Organization

Japan Organizing Committee

Chairman:
Shozo Saito, Device & System Platform Development Center Co., Ltd.

Vice Chairman:
Shuichi Inoue, ATONARP INC.

Treasurer
Hiroyuki Kamijo, TOSHIBA ELECTRONIC DEVICES & STORAGE Corp.

Member:
Atsuo Shimizu, Aizu Fujitsu Semiconductor Limited
Keiji Horioka, Applied Materials Japan, Inc.
Tadahiro Suhara, JSR Corp.
Michihiro Inoue, National Institute of Advanced Industrial Science and Technology (AIST)
Hiroyuki Umimoto, Panasonic Corp.
Masahiko Nozaki, Renesas Electronics Corp.
Shuichi Inoue, Renesas Semiconductor Manufacturing Co., Ltd.
Yasutoshi Okuno, SCREEN Semiconductor Solutions
Takahito Matsuzawa, Tokyo Electron Ltd.
Tomoyuki Sasaki, TowerJazz Panasonic Semiconductor
Atsuyoshi Koike, Western Digital Japan
Tadashi Nishimura

Japan Executive Committee

Chairman:
Ayako Shimazaki, Toshiba Nanoanalysis Corp.

Member:
Keiji Horioka, Applied Materials Japan, Inc.
Kensuke Uriga, Dura Systems, Inc.
Naoyuki Ishiwata, Fujitsu Semiconductor Limited
Takeshi Hattori, Hattori Consulting International
Hiroshi Akahori, KIOXIA Corp.
Toshiyuki Uchino, Kokusai Electric Inc.
Hiroyuki Umimoto, Panasonic Corp.
Hiroyuki Mori, Renesas Electronics Corp.
Takashi Shimane, Rohm Co., Ltd.
Yasutoshi Okuno, SCREEN Semiconductor Solutions Co., Ltd.
Hiroyuki Chuma, Seijo University
Masahiko Hamajima, SEMI
Kiyoshi Watanabe, Semiconductor Equipment Association of Japan (SEAJ)
Takahito Matsuzawa, Tokyo Electron, Ltd.
Kazuya Okamoto, Yamaguchi University Graduate School
Makoto Hirayama

Japan Program Committee

Chairman:
Toshiyuki Uchino, Kokusai Electric Corporation

Executive Vice Chairman:
Ayako Shimazaki, Toshiba Nanoanalysis Corp.
Shin-ichi Imai, Hitachi High-Tech Solutions Corp.

Committee leader:
Kazunori Kato, Advanced Interface Technology Corp.
Isamu Namose, Nidec Mobility Corp.
Katsutoshi Ozawa, OMRON Corp.

ISSM Conference Editor for IEEE TSM
Tsuyoshi Moriya, Tokyo Electron Technology Solutions Ltd.

Member:
Shinsuke Mizuno, Applied Materials Japan, Inc
Kazunori Nemoto, Hitachi High Technologies America, Inc.
Shuhei Murata, JX Nippon Mining & Metals Corporation
Masami Aoki, KLA-Tencor Japan Ltd.
Takahiro Tsuchiya, United Semiconductor Japan Co., Ltd.
Minoru Akaishi, ON Semiconductor
Masahiro Shimbo, ON Semiconductor
Kenji Miyake, PMT Corp.
Kazuki Yokota, Renesas Electronics Corp.
Toshiharu Katayama, Renesas Electronics Corp.
Shoji Takei, Rohm Co., Ltd.
Hiroaki Ochi, Rohm Co., Ltd.
Kenji Watanabe, SanDisk Ltd.
Takayuki Hisamatsu, Sony Semiconductor Manufacturing Corp.
Kazuhito Matsukawa, SUMCO Corp.
Hiroyuki Inoue, Texas Instruments Japan Limited
Yoichi Hori, TOKYO OHKA KOGYO Co., LTD.
Yuji Yamada, KIOXIA Corp.
Takatoshi Yasui, TowerJazz Panasonic Semiconductor Co., Ltd.
Sumika Arima, University of Tsukuba

e-Manufacturing & Design Collaboration Conference (eMCD) Advisory Committee

Dr. Nicky C.C. Lu, Etron Technology, Inc.
Dr. TY Wu, TSIA
Ms. Celia Shih, TSIA
Mr. Thomas Chen, tsmc
Mr. Robert Chien, tsmc
Dr. C. Hsu, tsmc
Prof. SC Chang, National Taiwan University

Sponsorship of ISSM2020 in Tokyo, Japan

	Platinum Sponsor	Gold Sponsor	Silver Sponsor	Bronze Sponsor
Sponsorship Fee	¥800,000	¥600,000	¥400,000	¥200,000
ISSM2020 Invitation (Free)				
Free ticket(s) for ISSM2020	6	4	2	1
ISSM2020 Website				
Company logo placed on ISSM2020 website	Yes	Yes	Yes	Yes
	Upper	Middle	Lower	Lower
Link to corporate website	Yes	Yes	Yes	Yes
ISSM2020 Proceedings				
Recognition of sponsorship in meeting materials along with company logo and link to corporate website	Yes	Yes	Yes	Yes
Company logo printed in color on the brochure on site	Yes	Yes	Yes	Yes
ISSM2020 Screen at site				
Company logo on the screen of interval	Yes	Yes	Yes	Yes
Company logo poster at the Symposium Room	Yes	Yes	Yes	Yes
Table top exhibition				
Provide table and white board at the Room	Yes	Yes	Yes	Yes

Contact:
ISSM Office
C/O Semiconductor Portal, Inc.
4F, Masonic 39MT Bldg., 2-4-5 Azabudai, Minato-ku, Tokyo 106-0041 Japan
TEL: +81-3-5733-4971
E-mail: issm_2020@semiconportal.com